

Title (en)
ELECTRIC WAVE ABSORPTION SHEET

Title (de)
ELEKTROWELLENABSORPTIONSFOLIE

Title (fr)
FEUILLE D'ABSORPTION D'ONDES ÉLECTRIQUES

Publication
EP 3478046 A4 20200219 (EN)

Application
EP 17815460 A 20170621

Priority
• JP 2016123493 A 20160622
• JP 2017022912 W 20170621

Abstract (en)
[origin: EP3478046A1] Provided is an electric-wave absorbing sheet that can favorably absorb high frequency electric waves in the millimeter-wave band or higher and that has high handleability. The electric-wave absorbing sheet includes a flexible electric-wave absorbing layer 1 that contains a particulate electric-wave absorbing material 1a and a resin binder 1b. The electric-wave absorbing material is a magnetic iron oxide that magnetically resonates at a frequency band equal to or higher than the millimeter-wave band.

IPC 8 full level
H05K 9/00 (2006.01); **B32B 15/08** (2006.01); **H01F 1/34** (2006.01); **H01Q 17/00** (2006.01)

CPC (source: EP US)
B32B 15/08 (2013.01 - EP US); **H01F 1/34** (2013.01 - EP US); **H01F 1/342** (2013.01 - US); **H01Q 17/004** (2013.01 - EP);
H05K 9/00 (2013.01 - US); **H05K 9/0075** (2013.01 - EP US); **B32B 2307/416** (2013.01 - US)

Citation (search report)
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• [Y] JP 2007193323 A 20070802 - FUJIFILM CORP
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• [Y] JP 2009059752 A 20090319 - HITACHI CHEMICAL CO LTD
• [Y] JP 2011181679 A 20110915 - TDK CORP
• [Y] JP 2006332260 A 20061207 - MURAZAKI HAJIME, et al
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Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 3478046 A1 20190501; **EP 3478046 A4 20200219**; JP 2019195083 A 20191107; JP 6764465 B2 20200930;
JP WO2017221992 A1 20180927; US 2019215994 A1 20190711; WO 2017221992 A1 20171228

DOCDB simple family (application)
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